Mentech 铭普光磁

RoHS

Product Specification

CUSTOMER：

DESCRIPTION： **PLC Transformer**

MNC P/N： T0874CE

REVISION： A0

CUSTOMER P/N：

ISSUED DATE： 2020-03-10

PHOTO OF PRODUCT：

WEIGHT：

PREPARED BY	CHECKED BY	APPROVED BY
Jingjing Fu	SC Wang	Lion Li

INDEX

CHANGE RECORD

REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
A0	Initial release	2020-03-10	Jingjing Fu

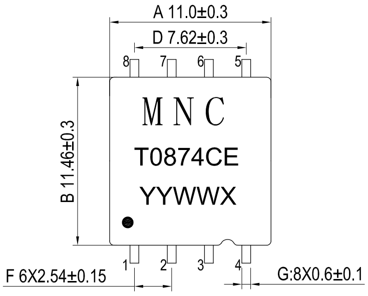
PLC Transformer
T0874CE

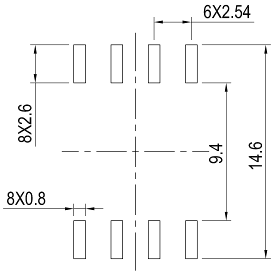
- DESIGN FOR PLC(POWER LINE COMMUNICATION) APPLICATION.
- ROHS COMPLIANT.
- FUNCTIONAL INSULATION.
- OPERATING TEMPERATURE RANGE: -40℃ TO +85℃.

Electrical Specifications @25°C

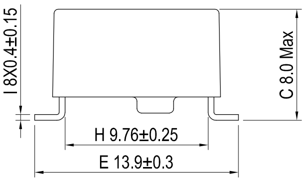
Part Number	Turns Ratio (100KHz,1V)	OCL (100KHz,0.1V)	LL (100KHz,0.1V)	Cww (100KHz,0.1V)	DCR	Insertion loss @2-80MHz	Return loss @2-80MHz	Hi-Pot
T0874CE	8-1:2-7:3-6:4-5	8-1,2-7,3-6,4-5	8-1 (tie2-7,3-6,4-5)	1-2 (tie7+3,6+4)	8-1,2-7,3-6,4-5	8-1 To 2-7,3-6,4-5	8-1 To 2-7,3-6,4-5	Pri TO Sec
	1:1:1:1±2%	300uH Min	0.6uH Max	25pF Max	0.5Ω Max	-1.4dB Max	-15dB Min	1500VAC 1.0mA,60S

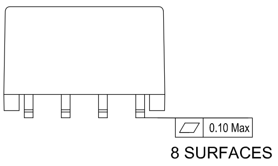
MECHANICAL DIMENSIONS(unit:mm)





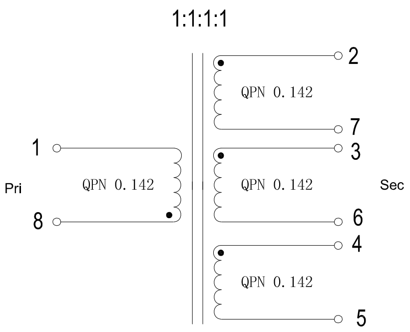
SUGGESTED PAD LAYOUT





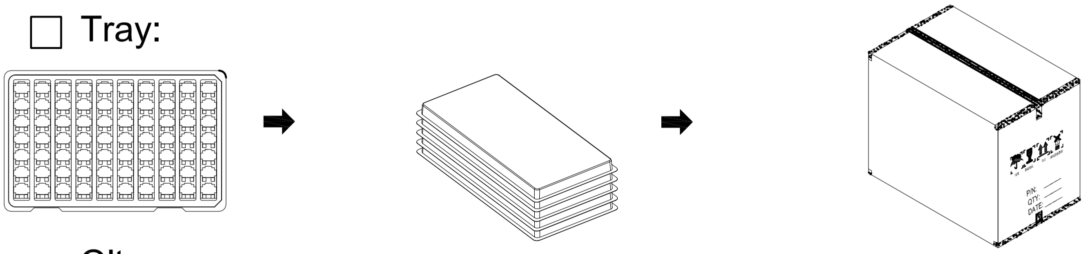
- Unless otherwise specified all tolerances are:±0.25 mm

SCHEMATICS



PACKING:

☐ Tray:

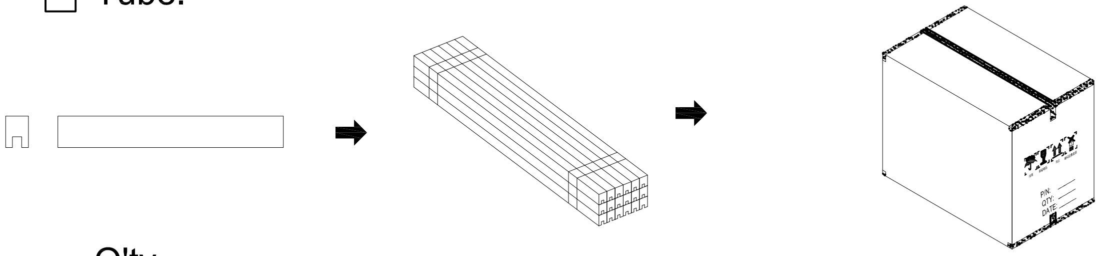


Q'ty

_______ PCS Per Tray

_______ PCS Per Carton

☐ Tube:

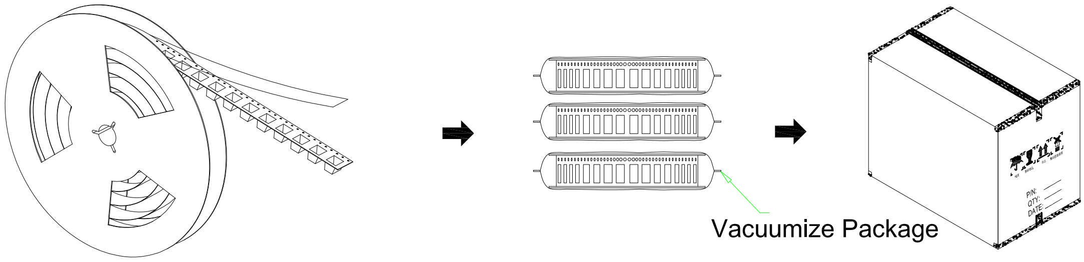


Q'ty

_______ PCS Per Tube

_______ PCS Per Carton

☑ Reel:



Q'ty

400 PCS Per Reel

2800 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

1. Level:1
2. Shelf Life:Unlimited
3. Storage Condition:≤30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

☑ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

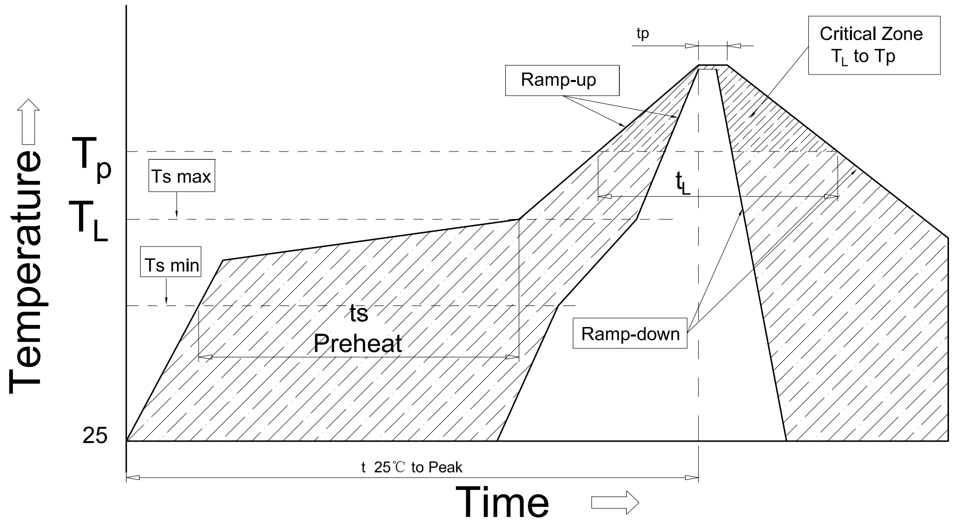


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3℃/second max	3℃/second max
Preheat -Temperature Min (Ts_{min}) -Temperature Max (Ts_{max}) -Time (ts_{min} to ts_{max})	100℃ 150℃ 60-120 seconds	150℃ 200℃ 60-180 seconds
Time maintained above: -Temperature (T_L) -Time (t_L)	183℃ 60-150 seconds	217℃ 60-150 seconds
Peak/Classification Temperature(T_p)	See IPC/JEDEC J-STD-020CTable 4-1	See IPC/JEDEC J-STD-020CTable 4-2
Time within 5℃ of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6℃/second max	6℃/second max
Time 25℃ to Peak Temperature	6 minutes max	8 minutes max

Note1:All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
  Solder Paste: Sn96.5Ag3.0Cu0.5
  Silkscreen thickness:0.15mm Min.

☐ 2. Wave soldering profile